LISTING OF THE CLAIMS

Pursuant to 37 C.F.R. §1.121, provided below is a listing of the claims, claims 1-15.

1.   (Currently amended) A system for measuring fault coverage in an integrated circuit (IC), comprising:

a Device Under Test (DUT) assembly including said IC, wherein said IC includes at least one node operable to be stimulated to a temporary stuck-at fault condition by a ~~certain~~ frequency of electromagnetic (EM) radiation;

a probe operable to stimulate said DUT assembly with said frequency of EM radiation to create said temporary stuck-at fault condition at one or more nodes of said IC; and

a test pattern generator and interface system interfacing with said DUT assembly, said test pattern generator and interface system operating to apply a test vector to said DUT assembly and receive a corresponding response, wherein said corresponding response is indicative of a fault coverage measurement.

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2. (Original) The system for measuring fault coverage in an IC as recited in claim 1, wherein said IC is disposed on a die.

3. (Original) The system for measuring fault coverage in an IC as recited in claim 1, wherein said IC is disposed on a wafer.

4. (Original) The system for measuring fault coverage in an IC as recited in claim 1, wherein said IC is disposed on a packaged chip.

5. (Original) The system for measuring fault coverage in an IC as recited in claim 1, wherein said probe comprises a laser voltage probe.

6. (Currently amended) The system for measuring fault coverage in an IC as recited in claim 1, wherein said temporary stuck-at fault condition comprises a stuck-at-zero condition.

7. (Currently amended) The system for measuring fault coverage in an IC as recited in claim 1, wherein said temporary stuck-at fault condition comprises a stuck-at-one condition.

8. (Currently amended) A method for measuring fault coverage in an integrated circuit (IC), comprising:

stimulating a select number of nodes associated with said IC with a ~~certain~~ frequency of electromagnetic (EM) radiation;

creating a temporary stuck-at fault condition at each of said select number of nodes;

applying a test vector set to said IC upon creating said temporary stuck-at fault condition at each of said select number of nodes;

comparing said IC's output against expected results associated with said test vector set; and

determining fault coverage as a percentage of said temporary stuck-at fault conditions detected by said test vector set.

9.   (Currently amended) The method as recited in claim 8, wherein said ~~certain~~ frequency of EM is supplied by a laser voltage probe system.

10.   (Currently amended) The method as recited in claim 8, wherein said <u>temporary</u> stuck-at fault condition comprises a stuck-at-zero condition.

11.   (Currently amended) The method as recited in claim 8, wherein said <u>temporary</u> stuck-at fault condition comprises a stuck-at-one condition.

12.   (Currently amended) A   system   for   measuring fault coverage in an integrated circuit (IC), comprising:

means for stimulating a _temporary_ stuck-at fault condition at _each of_ a select number of nodes associated with said IC with a ~~certain~~ frequency of electromagnetic (EM) radiation;

means for applying a test vector set to said IC upon creating said _temporary_ stuck-at fault condition _at each of said select number of nodes_;

means for comparing said IC's output against expected results associated with said test vector set; and

means for determining fault coverage as a percentage of said _temporary_ stuck-at fault conditions detected by said test vector set.

13.   (Currently amended) The system for measuring fault coverage in an IC as recited in claim 12, wherein said means for stimulating a _temporary_ stuck-at fault condition comprises a laser voltage probe system.

14.   (Currently amended) The system for measuring fault coverage in an IC as recited in claim 12, wherein said _temporary_ stuck-at fault condition comprises a stuck-at-zero condition.

15.   (Currently amended) The system for measuring fault coverage in an IC as recited in claim 12, wherein said _temporary_ stuck-at fault condition comprises a stuck-at-one condition.